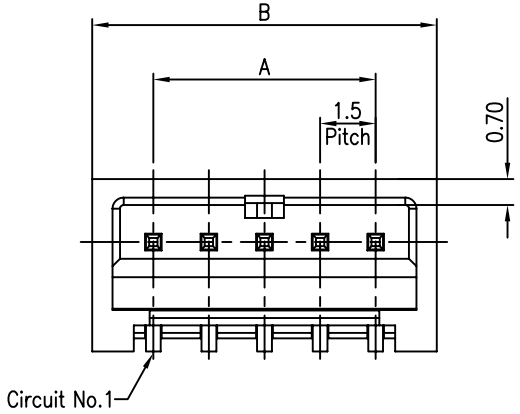
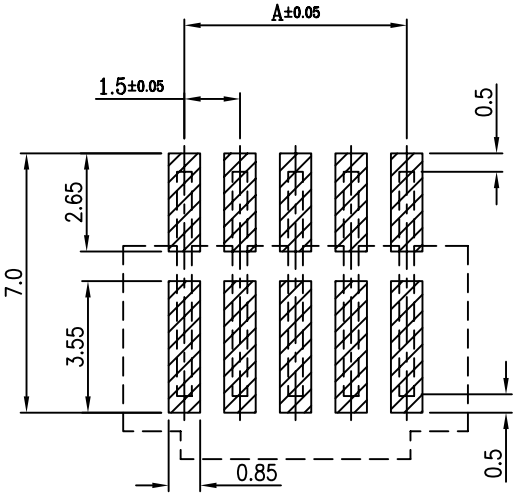
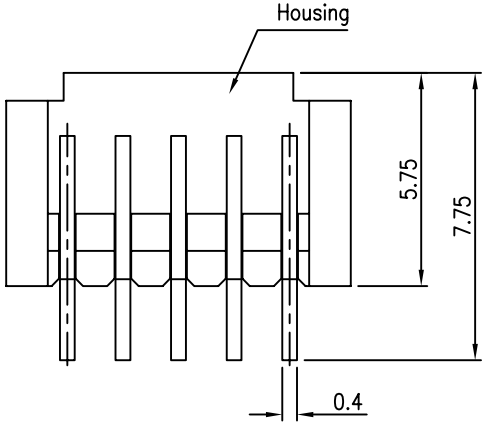
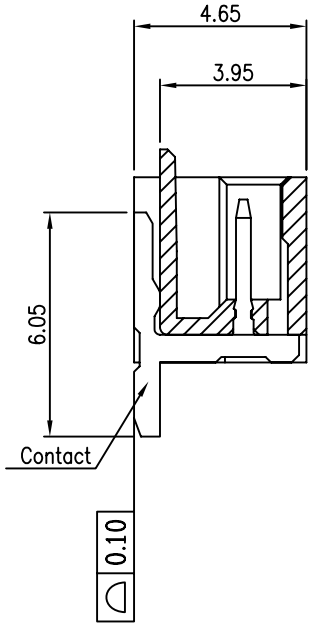




RECOMMENDED PCB LAYOUT
GENERAL TOLERANCE ±0.05





NOTES:
1. MATERIAL:
   1.1 HOUSING: HALOGEN FREE PLASTIC, HIGH TEMP., UL94V-0.
   1.2 CONTACT: COPPER ALLOY
   1.3 FITTING NAIL: COPPER ALLOY
2. FINISH:
   2.1 CONTACT:
      1: 50u"MIN NICKEL UNDER PLATING OVER ALL GOLD FLASH ON CONTACT AREA
      L:50u"MIN NICKEL UNDER PLATING OVER ALL 80u"MIN. PURE TIN ON CONTACT AREA
      N:50u"MIN NICKEL UNDER PLATING OVER ALL 80u"MIN.MATT TIN ON CONTACT AREA
   2.2 SOLDER:
      1: 50u"MIN NICKEL UNDER PLATING OVER ALL GOLD FLASH ON SOLDER AREA
      L:50u"MIN NICKEL UNDER PLATING OVER ALL 80u"MIN.PURE TIN ON SOLDER AREA
      N:50u"MIN NICKEL UNDER PLATING OVER ALL 80u"MIN.MATT TIN ON SOLDER AREA
   2.3 FITTING NAIL:
      1:50u"MIN NICKEL UNDER PLATING OVER ALL GOLD FLASH ON SOLDER TAILS
      L:50u"MIN NICKEL UNDER PLATING OVER ALL 50u"MIN PURE TIN ON SOLDER TAILS
      N:50u"MIN NICKEL UNDER PLATING OVER ALL 120u"MIN.MATT TIN ON SOLDER TAILS
3. REFLOW SOLDER CAPABLE TO 260°C PER ACES SPEC.
4. SPEC. PLS. REFER TO PS-50289-xxxxx-xxx
5. PACKAGE PLS. REFER TO 50290-XXXX-TRP
6. PART NUMBER

P/N LEGEND
50493-XXX X X-XXX

XXX	COLOR	Halogen Free	Packing
001	BLACK	HF	EN-50493-XXXXX-XX-TRP

NO OF CKT
PACKING
0:TAPE & REEL
1:TUBE
PLATING
L:LEAD FREE (PURE TIN)
N:MATT TIN
1:G/F OVERALL

CKT	Dim A	Dim B
2	1.5	4.8
3	3.0	6.3
4	4.5	7.8
5	6.0	9.3
6	7.5	10.8
7	9.0	12.3
8	10.5	13.8
9	12.0	15.3
10	13.5	16.8
11	15.0	18.3
12	16.5	19.8
13	18.0	21.3
14	19.5	22.8
15	21.0	24.3
16	22.5	25.8
17	24.0	27.3
18	25.5	28.8
19	27.0	30.3
20	28.5	31.8

一般公差
TOLERANCES
X. ±0.50 .XX ±0.15
.X ±0.25 .XXX ±0.10
ANGLES ±2°

宏致電子股份有限公司
Aces Electronic Co.,Ltd.

檢驗尺寸標示
SYMBOLS Ⓒ Ⓜ INDICATE CLASSIFICATION DIMENSION
Ⓒ MARK IS CRITICAL DIM.
Ⓜ MARK IS MAJOR DIM.

品名 (TITLE): 1.5mm WTB Header SMT R/A Type
圖號 (DWG.NO): 50493-XXXXX-XXX
表面處理 (FINISH):
比例 (SCALE): 1:1
單位 (UNITS): mm
製圖 (DR): 11/12/23 CHUNBO
審核 (CHKD): SAM
核准 (APPD): JASON
張數 (SHEET): 1 OF 1
SIZE: A4
REV: 0